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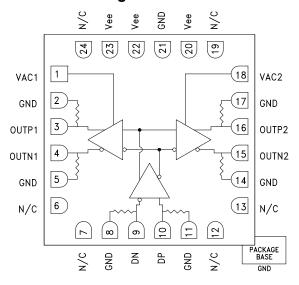


Typical Applications

The HMC842LC4B is ideal for:

- OC-768 and SDH STM-256 Equipment
- RF ATE Applications
- Short, intermediate, & Long Haul Fiber Optic Applications
- Broadband Test & Measurement
- Serial Data Transmission up to 45 Gbps
- Clock Buffering up to 28 GHz

Functional Diagram



Features

Supports Clock Frequencies up to 28 GHz

Independent Programmable Output Swing for Each Channel: 400 - 1200 mVp-p Diff.

Supports Single-Ended or Differential Operation

Power Consumption: 465 mW

Less than 500 fs Additive RMS Jitter

Fast Rise and Fall Times: <12ps

24 Lead 4x4mm SMT Package: 16mm²

General Description

The HMC842LC4B is a 1:2 Fanout Buffer designed to support data transmission rates up to 45 Gbps. The device can also operate with clock signals up to 28 GHz. During normal operation, input data (or clock) is transferred to both output channels. Differential input and output signals of the HMC842LC4B are terminated with 50 Ohms to ground on-chip, and may be either AC or DC coupled. The Outputs can be connected directly to a 50 Ohms-to-ground terminated system, while DC blocking capacitors should be used if the terminating system is 50 Ohms to a non-ground DC voltage.

The HMC842LC4B also features two separate output level control pins, VAC1 and VAC2 which provide loss compensation and signal level optimization for each output channel independently. The HMC842LC4B operates from a single -3.3V DC supply and is available in a ceramic RoHS compliant 4 x 4 mm SMT package.

Electrical Specifications, $T_A = +25$ °C, Vee = -3.3V

| Parameter | Conditions | Min. | Тур. | Max | Units | |
|---|--|-------|------|-------|-------|--|
| Power Supply Voltage | ±5 % Tolerance | -3.47 | -3.3 | -3.13 | V | |
| Power Supply Current | VAC1 = VAC2 = -0.3V (Vout = 930 mVp-p diff @ 40 Gbps) | 120 | 140 | 160 | mA | |
| Output Amplitude Control Voltage [1] (VAC1, VAC2) | | -1.4 | -0.3 | 0 | V | |
| Maximum Data Rate | | 45 | | | Gbps | |
| Maximum Clock Rate | | 28 | 32 | | GHz | |
| Input Amplitude | Single-ended, peak-to-peak | 50 | | 1000 | mVp-p | |
| Input Amplitude | Differential, peak-to-peak | 100 | | 2000 | шур-р | |
| Input High Voltage | | -0.5 | | 0.5 | V | |
| Input Low Voltage | | -1 | | 0 | V | |



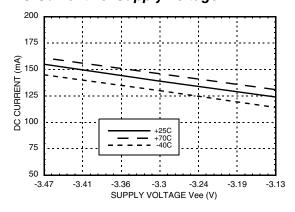


Electrical Specifications, (continued)

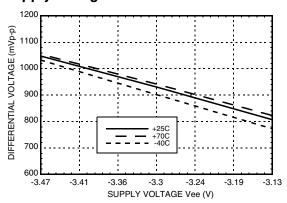
| Parameter | Conditions | Min. | Тур. | Max | Units |
|---|--------------------------------------|------------|------|------|--------|
| Output Amplitude | Differential, peak-to-peak @ 40 Gbps | 400 | | 1200 | mVp-p |
| Output High Voltage | | VAC = -0.3 | -10 | | mV |
| Output Low Voltage | | VAC = -0.3 | -550 | | mV |
| Input Return Loss | frequency < 32 GHz | | 10 | | dB |
| Output Return Loss | frequency < 32 GHz | | 7 | | dB |
| Deterministic Jitter, Jd [2] | | | 3 | | ps, pp |
| Additive Random Jitter Jr | @ 28 GHz Clock Input | | | 0.3 | ps rms |
| Additive Handom Sitter Sr | @ 32 GHz Clock Input | | | 0.6 | ps rms |
| Rise Time, tr [2] | | | 11 | | ps |
| Fall Time, tf [2] | | | 11 | | ps |
| Propagation Delay, td | | | 10 | | ps |
| OUT1 to OUT2 Data Skew, t _{skew} [2] | | | 2 | | ps |

^[1] VAC1=VC2 and VAC2=VC1 on evaluation board

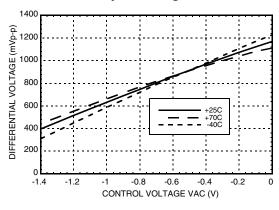
DC Current vs. Supply Voltage [1] [2]



Differential Output Swing vs. Supply Voltage [1] [2]



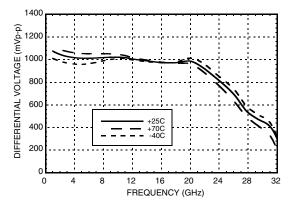
Differential Output Swing vs. VAC [3]



[1] VAC = -0.3V [2] Inp

[2] Input data rate: 40 Gbps PRBS 2^{23} -1

Differential Output Swing vs. Frequency [1]



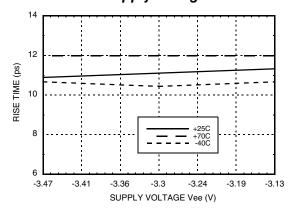
[3] Frequency = 20 GHz

^[2] Data Input: 40 Gbps PRBS 2²³-1 pattern, 150 mVp-p single-ended

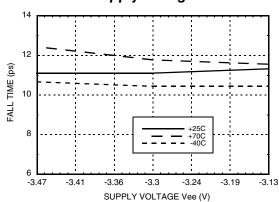




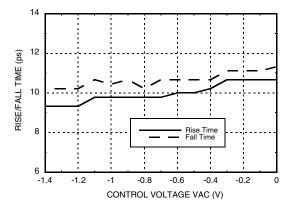
Rise Time vs. Supply Voltage [1][2][3]



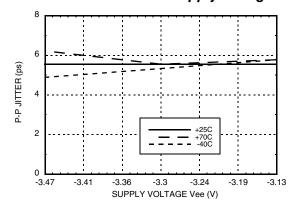
Fall Time vs. Supply Voltage [1][2][3]



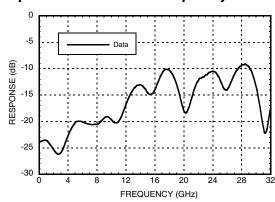
Rise / Fall Time vs. VAC [1][2][3]



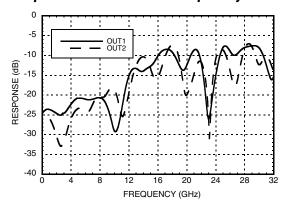
Peak-to-Peak Jitter vs. Supply Voltage [1][2][3][4]



Input Return Loss vs. Frequency [1][5]



Output Return Loss vs. Frequency [1][5]



[1] VAC = -0.3V

[2] Input data rate: 40 Gbps PRBS 223-1 [4] Source jitter was not deembeded

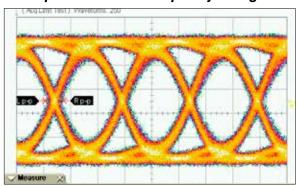
[3] Data was taken at single ended output

[5] Device measured on evaluation board with single-ended time domain gating





40 Gbps Differential Output Eye Diagram



| Measurements | | | | |
|--------------|-----------------|----------|----------------|----|
| | Current Min Max | | Total Meas. | |
| Eye Amp | 921 mV | 920 mV | 922 mV | 75 |
| Rise Time | 11.11 ps | 10.89 ps | 11.11 ps | 75 |
| Fall Time | 11.11 ps | 10.44 ps | 11.11 ps | 75 |
| p-p Jitter | 5.778 ps | 5.333 ps | 5.778 ps | 75 |

Time Scale: 10 ps/div Amplitude Scale: 210 mV/div

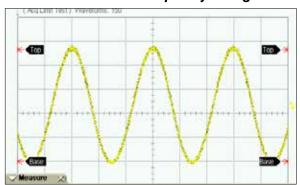
Test Conditions:

Vee = -3.3V, VAC = -0.3V

Input Data: Single ended 150 mVp-p 40 Gbps NRZ

PRBS 2²³-1 pattern

28 GHz Differential Output Eye Diagram



| Measurements | | | | |
|--------------|----------------------|----------|-----------|-----------|
| | Current Mean Min Max | | | |
| V Amp | 558.99 mV | 556.8 mV | 543.46 mV | 577.62 mV |
| Rise Time | 6.86 ps | 6.816 ps | 6.28 ps | 7.43 ps |
| Fall Time | 6.91 ps | 6.473 ps | 5.84 ps | 7.01 ps |

Time Scale: 12 ps/div Amplitude Scale: 120 mV/div

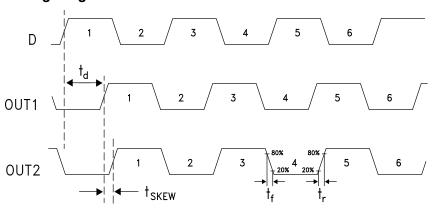
Test Conditions:

Vee = -3.3V, VAC = -0.3V

Input Data: Single ended 300 mVp-p 28 GHz clock

signal

Timing Diagram



| Input | Outputs | | |
|---|---------------------------------|------|--|
| D | OUT1 | OUT2 | |
| L | L | L | |
| Н | Н | Н | |
| Notes: D = DP - DN OUT1 = OUTP1 - OUTN1 OUT2 = OUTP2 - OUTN2 | H - Logic High L - Logic Low | | |





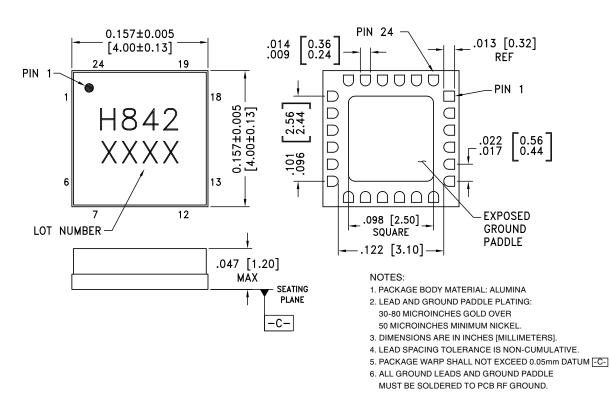
Absolute Maximum Ratings

| Power Supply Voltage (Vee) | -3.7V to +0.5V |
|--|-----------------|
| Input Voltage | -1.3V to +0.5V |
| Channel Temperature | 125°C |
| Continuous Pdiss (T = 85°C) (derate 18.48 mW/°C above 85°C) | 0.74 W |
| Thermal Resistance (channel to ground paddle) | 54.11 °C/W |
| Storage Temperature | -65°C to +125°C |
| Operating Temperature | -40°C to +70°C |
| Output Amplitude Control Voltage (VAC) | -2.3V to +0.5V |



Outline Drawing

BOTTOM VIEW



Package Information

| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking [2] |
|-------------|-----------------------|------------------|---------------------|---------------------|
| HMC842LC4B | Alumina, White | Gold over Nickel | MSL3 ^[1] | H842 XXXX |

^[1] Max peak reflow temperature of 260 $^{\circ}\text{C}$

^{[2] 4-}Digit lot number XXXX





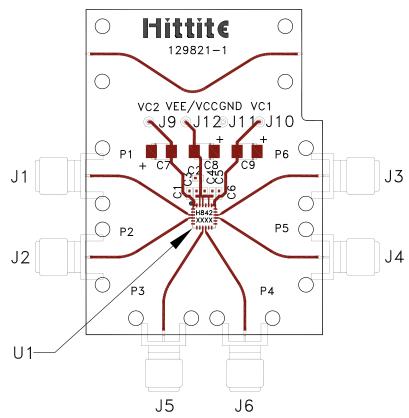
Pin Descriptions

| Pin Number | Function | Description | Interface Schematic |
|--|--------------|--|--------------------------|
| 1 | VAC1 | Output Amplitude Control Voltage for OUT1 Note: VAC1=VC2 on evaluation board | VAC1 O Vee |
| 2, 5, 8, 11, 14, 17, 21 Package Bottom | GND | Signal and supply grounds | ○ GND = |
| 3, 4 | OUTP1, OUTN1 | Differential (OUTP1-OUTN1) or single ended (OUTP1) outputs | GND O 60 O OUTP1 OUTN1 |
| 6, 7, 12, 13, 19, 24 | N/C | The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally. | |
| 9, 10 | DN, DP | Differential (DP-DN) or single ended (DP) inputs | GND 60 Ω DN, DP Vee |
| 15, 16 | OUTN2, OUTP2 | Differential (OUTP2-OUTN2) or single ended (OUTP2) outputs | GND O OUTP2 OUTN2 |
| 18 | VAC2 | Output Amplitude Control Voltage for OUT2 Note: VAC2=VC1 on evaluation board | VAC2 O Vee |
| 20, 22, 23 | Vee | Power Supply (-3.3V) | |





Evaluation PCB



| Item | Description |
|------|-------------|
| J1 | OUTP1 |
| J2 | OUTN1 |
| J3 | OUTP2 |
| J4 | OUTN2 |
| J5 | DN |
| J6 | DP |
| J9 | VAC1 |
| J10 | VAC2 |
| J11 | GND |
| J12 | Vee |

Note: VC1 on evaluation board is VAC2 and VC2 on evaluation board is VAC1

List of Materials for Evaluation PCB 129151 [1]

| Item | Description |
|-------------|------------------------------|
| J1 - J6 | K Connector |
| J9 - J12 | DC Pin |
| C1, C3 - C6 | 1000 pF Capacitor, 0402 Pkg. |
| C2 | 0.1 μF Capacitor, 0402 Pkg. |
| C7 - C9 | 4.7 μF Capacitor, Tantalum |
| U1 | HMC842LC4B 1:2 Fanout Buffer |
| PCB [2] | 129821 Evaluation Board |

 $[\]ensuremath{[1]}$ Reference this number when ordering complete evaluation PCB

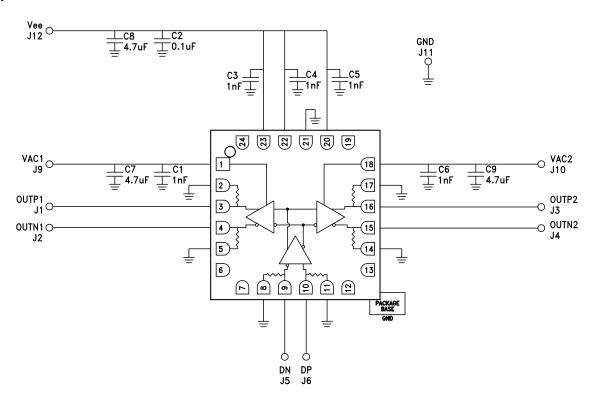
The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed metal package base must be connected to Vee. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Arlon 25FR or Rogers 4350





Application Circuit



Note: VAC1(J9)=VC2 and VAC2(J10)=VC1 on evaluation board.

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HMC842LC4B 129151-HMC842LC4B